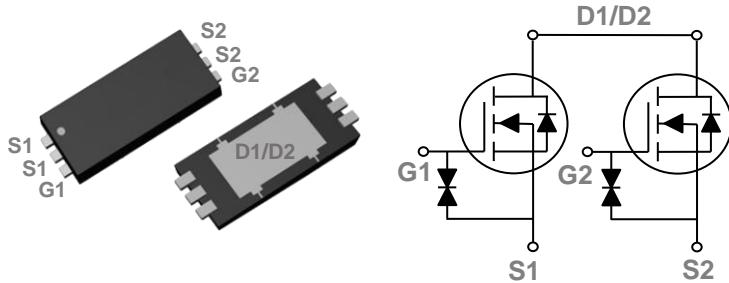


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK2x5 Dual Pin Configuration



BVDSS	RDSON	ID
20V	9.6mΩ	20A

Features

- 20V,20A, $RDS(ON) = 9.6\text{m}\Omega$ @ $VGS = 4.5\text{V}$
- Improved dv/dt capability
- Fast switching
- G-S ESD Protection Diode Embedded
- Green Device Available

Applications

- Handheld Instruments
- POL Applications
- Battery Protection Applications

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	20	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	12.6	A
I_{DM}	Drain Current – Pulsed ¹	80	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	27	W
	Power Dissipation – Derate above 25°C	0.22	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to case	---	4.55	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	20	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=85^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 20	μA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ³	$V_{\text{GS}}=4.5\text{V}$, $I_D=2.4\text{A}$	---	8	9.6	$\text{m}\Omega$
		$V_{\text{GS}}=4.0\text{V}$, $I_D=2.4\text{A}$	---	8.2	9.8	$\text{m}\Omega$
		$V_{\text{GS}}=3.7\text{V}$, $I_D=2.4\text{A}$	---	8.5	10.6	$\text{m}\Omega$
		$V_{\text{GS}}=3.1\text{V}$, $I_D=2.4\text{A}$	---	9.1	11.8	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$, $I_D=2.4\text{A}$	---	10.3	13.4	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	0.5	0.65	1.5	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_D=5\text{A}$	---	15	---	S

Dynamic and switching Characteristics

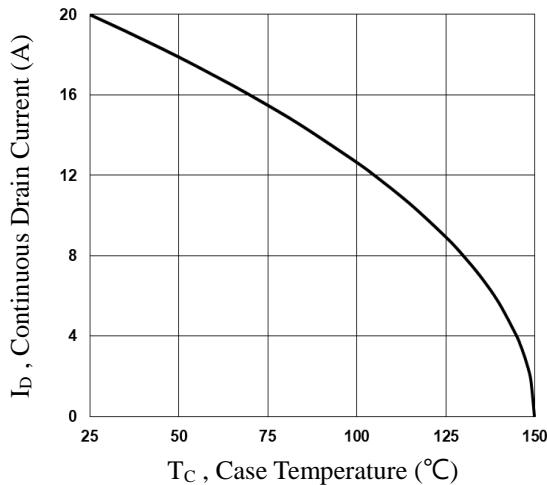
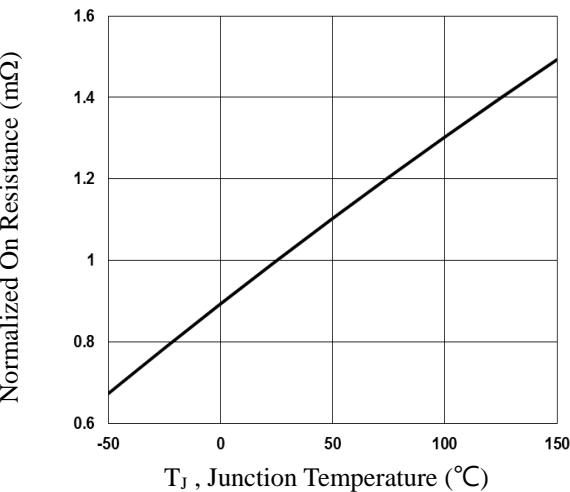
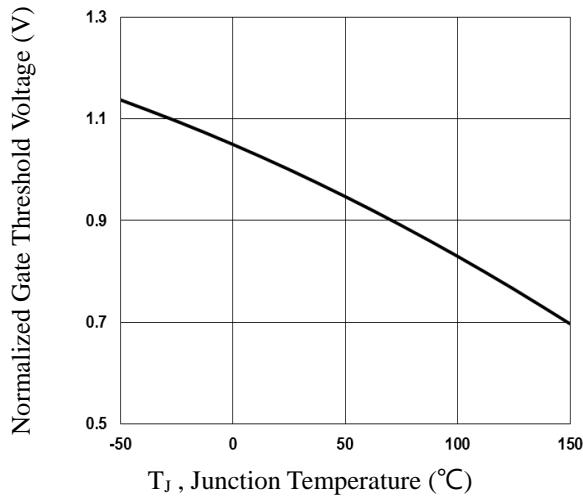
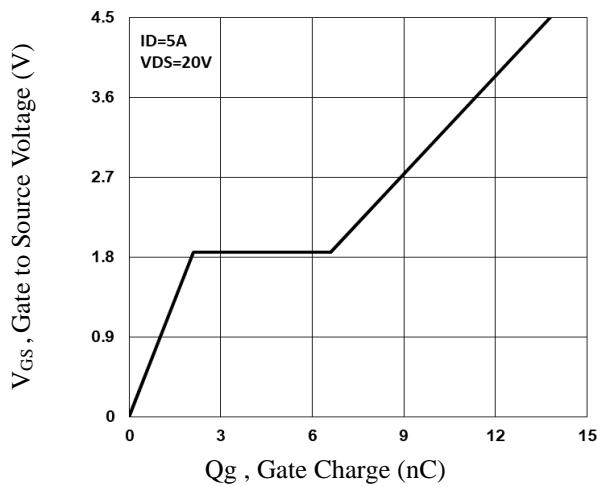
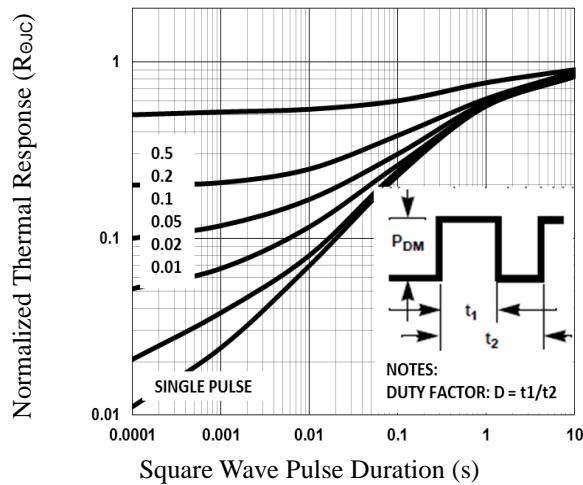
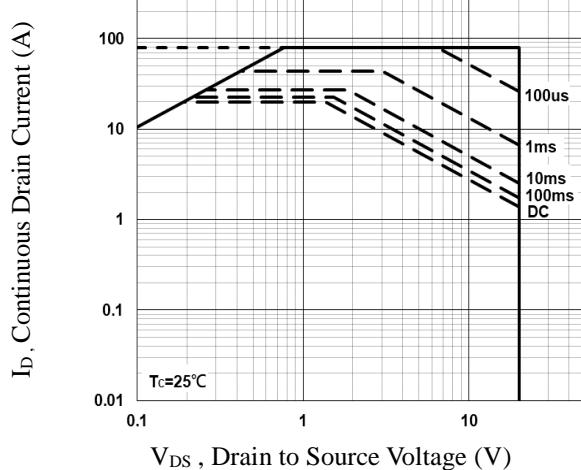
Q_g	Total Gate Charge ^{2,3}	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=5\text{A}$	---	13.8	---	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	2.1	---	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	4.5	---	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=6\Omega$ $I_D=5\text{A}$	---	28	---	ns
T_r	Rise Time ^{2,3}		---	64	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{2,3}		---	60	---	
T_f	Fall Time ^{2,3}		---	55	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	1514	---	pF
C_{oss}	Output Capacitance		---	178	---	
C_{rss}	Reverse Transfer Capacitance		---	145	---	

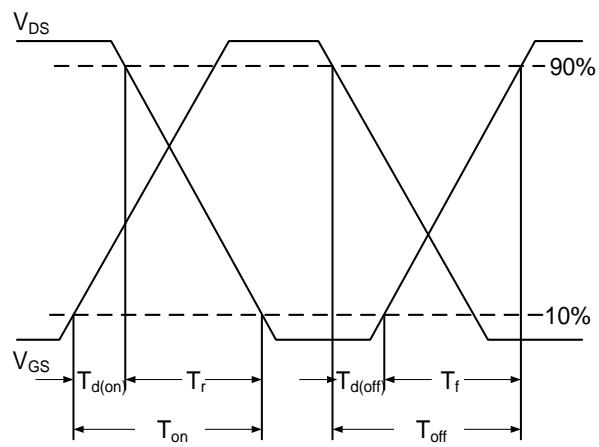
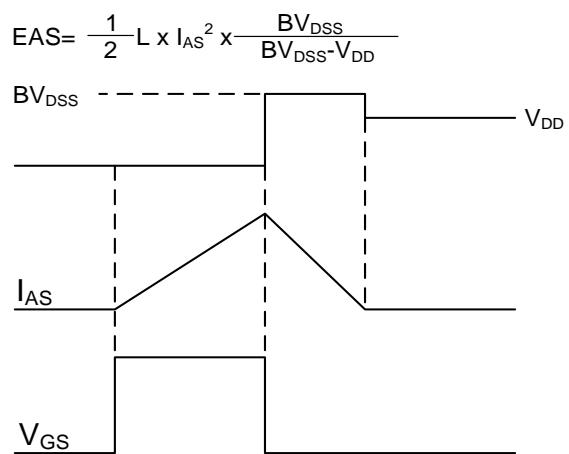
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	20	A
I_{SM}	Pulsed Source Current		---	---	40	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

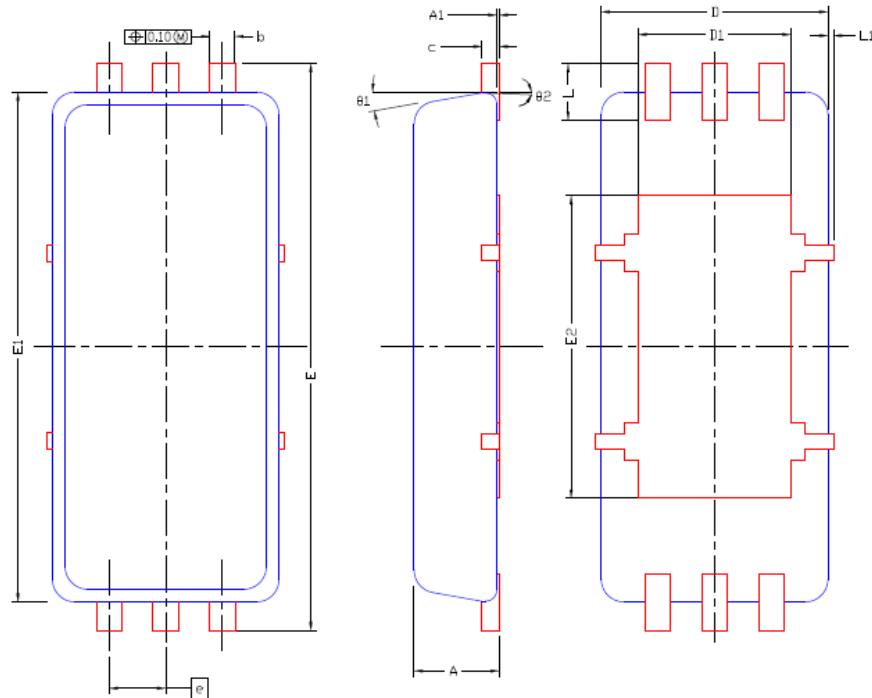
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_C

Fig.2 Normalized RDSON vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Response

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 EAS Waveform

PPAK2X5 PACKAGE INFORMATION



DIM.	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.70	0.75	0.80	0,028	0,030	0,0315
A1	0.00	---	0.05	0,000	---	0,002
b	0.20	0.225	0.30	0,008	0,009	0,012
c	0.10	0.152	0.20	0,004	0,006	0,008
D	2.00 BSC			0.079 BSC		
D1	1.30	1.35	1.55	0,051	0,053	0,061
E	5.00 BSC			0.197 BSC		
E1	4.50 BSC			0.177 BSC		
E2	2.60	2.67	2.95	0,102	0,105	0,116
e	0.50 BSC			0,020 BSC		
L	0.40	0.50	0.600	0,016	0,0197	0,0236
L1	0	---	0.100	0	---	0,004
θ1	0°	10°	12°	0°	10°	12°
θ2	3° BSC			3° BSC		